

### Identification

**DVM16R2S4/16G** 2Gx72  
16GB 2Rx4 PC3-12800R-11

### Performance Range

Clock / Module Speed / CL-t<sub>RCD</sub> -t<sub>RP</sub>  
800 MHz / PC3-12800 / 11-11-11  
667 MHz / PC3-10600 / 10-10-10  
667 MHz / PC3-10600 / 9-9-9  
533 MHz / PC3-8500 / 8-8-8  
533 MHz / PC3-8500 / 7-7-7  
400 MHz / PC3-6400 / 6-6-6



### Features

240-pin JEDEC-compliant DIMM, 133.35 mm wide by 30.00 mm high  
Operating Voltage: 1.5V ±0.075  
I/O Type: SSTL\_15  
On-board I<sup>2</sup>C temperature sensor with integrated Serial Presence-Detect (SPD) EEPROM  
Data Transfer Rate: 12.8 Gigabytes/sec  
Data Bursts: 8 and burst chop 4 mode  
ZQ Calibration for Output Driver and On-Die Termination (ODT)  
Programmable ODT / Dynamic ODT during Writes  
Programmable CAS Latency: 6, 7, 8, 9, 10 and 11  
Bi-directional Differential Data Strobe signals  
SDRAM Addressing (Row/Col/BG/BA): 16/11/3  
Fully RoHS Compliant

### Description

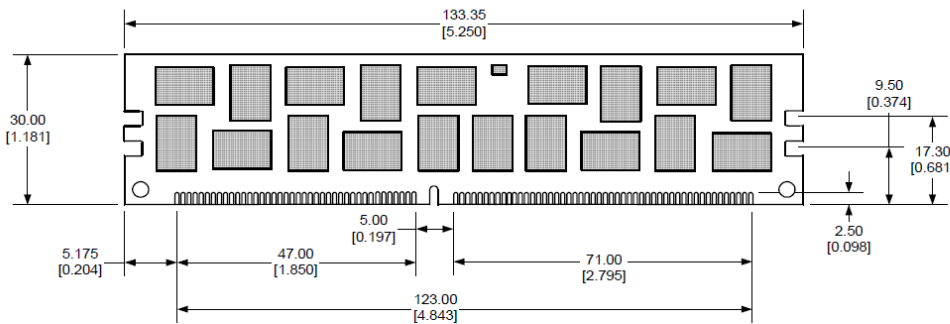
**DVM16R2S4/16G** is a registered 2Gx72 memory module, which conforms to JEDEC's DDR3-1600, PC3-12800 standard. The assembly is Dual Rank. Each rank is comprised of eighteen 1Gbx4 DDR3 SDRAMs.

One EEPROM is used for Serial Presence Detect and a combination register/PLL, with Address and Command Parity, is also used.

Both output driver strength and input termination impedance are programmable to maintain signal integrity on the I/O signals in a Fly-by topology.

A thermal sensor accurately monitors the DIMM module and can prevent exceeding the maximum operating temperature of 95C.

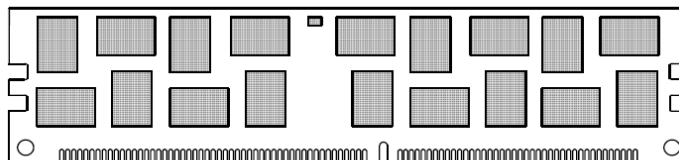
Front view



### Notes

Tolerances on all dimensions except where otherwise indicated are ±.13 (.005).  
All dimensions are expressed in millimeters [inches]

Back view



Side view

